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To Our Customers

Continuing it's rich tradition of partnering with high quality Japanese semiconductor suppliers, CEL is now partnering with THine from May of 2015 onwards.

THC63LVDM83C(5S)

REDUCED SWING LVDS 24Bit COLOR HOST-LCD PANEL INTERFACE

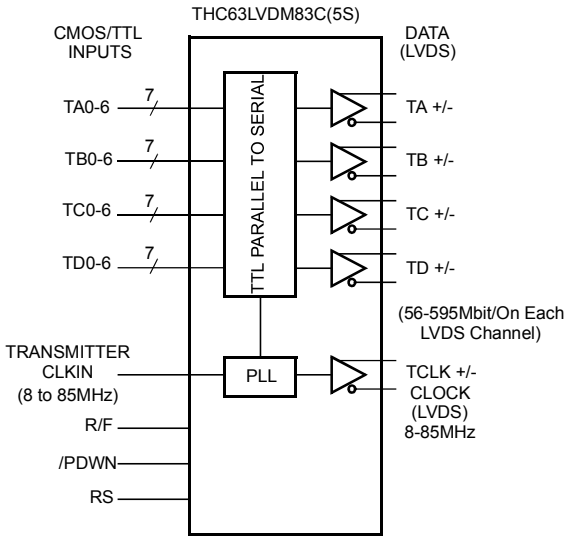
General Description

The THC63LVDM83C(5S) transmitter is designed to support pixel data transmission between Host and Flat Panel Display from NTSC up to SXGA+ resolutions. The THC63LVDM83C(5S) converts 28bits of CMOS/TTL data into LVDS(Low Voltage Differential Signaling) data stream. The transmitter can be programmed for rising edge or falling edge clocks through a dedicated pin. At a transmit clock frequency of 85MHz, 24bits of RGB data and 4bits of timing and control data (HSYNC, VSYNC, CNTL1, CNTL2) are transmitted at an effective rate of 595Mbps per LVDS channel.

Features

- Wide dot clock range: 8-85MHz suited for NTSC, VGA, SVGA, XGA
- PLL requires no external components
- Supports spread spectrum clock generator
- On chip jitter filtering
- Clock edge selectable
- Supports reduced swing LVDS for low EMI
- Power down mode
- Low power single 3.3V CMOS design
- Low profile 56 Lead TSSOP Package
- 1.2 up to 3.3V tolerant data inputs to connect directly to low power,low voltage application and graphic processor.
- Backward compatible with THC63LVDM83R(24bits)

Block Diagram



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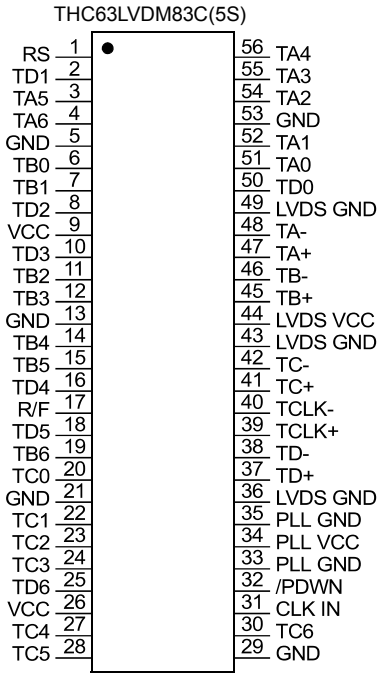
Pin Out


THC63LVDM83C(5S)
RS 1
TD1 2
TA5 3
TA6 4
GND 5
TB0 6
TB1 7
TD2 8
VCC 9
TD3 10
TB2 11
TB3 12
GND 13
TB4 14
TB5 15
TD4 16
R/F 17
TD5 18
TB6 19
TC0 20
GND 21
TC1 22
TC2 23
TC3 24
TD6 25
VCC 26
TC4 27
TC5 28
56 TA4
55 TA3
54 TA2
53 GND
52 TA1
51 TA0
50 TD0
49 LVDS GND
48 TA-
47 TA+
46 TB-
45 TB+
44 LVDS VCC
43 LVDS GND
42 TC-
41 TC+
40 TCLK-
39 TCLK+
38 TD-
37 TD+
36 LVDS GND
35 PLL GND
34 PLL VCC
33 PLL GND
32 /PDWN
31 CLK IN
30 TC6
29 GND

Pin Description

<table>
<tr><th>Pin Name</th><th>Pin #</th><th>Type</th><th>Description</th></tr>
<tr><td>TA+, TA-</td><td>47, 48</td><td>LVDS OUT</td><td rowspan="4">LVDS Data Out.</td></tr>
<tr><td>TB+, TB-</td><td>45, 46</td><td>LVDS OUT</td></tr>
<tr><td>TC+, TC-</td><td>41, 42</td><td>LVDS OUT</td></tr>
<tr><td>TD+, TD-</td><td>37, 38</td><td>LVDS OUT</td></tr>
<tr><td>TCLK+, TCLK-</td><td>39, 40</td><td>LVDS OUT</td><td>LVDS Clock Out.</td></tr>
<tr><td>TA0 ~ TA6</td><td>51, 52, 54, 55, 56, 3, 4</td><td>IN</td><td rowspan="4">Pixel Data Inputs.</td></tr>
<tr><td>TB0 ~ TB6</td><td>6, 7, 11, 12, 14, 15, 19</td><td>IN</td></tr>
<tr><td>TC0 ~ TC6</td><td>20, 22, 23, 24, 27, 28, 30</td><td>IN</td></tr>
<tr><td>TD0 ~ TD6</td><td>50, 2, 8, 10, 16, 18, 25</td><td>IN</td></tr>
<tr><td>/PDWN</td><td>32</td><td>IN</td><td>H: Normal operation,
L: Power down (all outputs are Hi-Z)</td></tr>
<tr><td>RS</td><td>1</td><td>IN</td><td>LVDS swing mode, VREF select.
<table><tr><th>RS</th><th>LVDS Swing</th><th>Small Swing Input Support</th></tr><tr><td>VCC</td><td>350mV</td><td>N/A</td></tr><tr><td>0.6 ~ 1.4V</td><td>350mV</td><td>RS=VREF[a]</td></tr><tr><td>GND</td><td>200mV</td><td>N/A</td></tr></table>a. VREF is Input Reference Voltage.</td></tr>
<tr><td>R/F</td><td>17</td><td>IN</td><td>Input Clock Triggering Edge Select.
H: Rising edge, L: Falling edge</td></tr>
<tr><td>VCC</td><td>9, 26</td><td>Power</td><td>Power Supply Pins for TTL inputs and digital circuitry.</td></tr>
<tr><td>CLKIN</td><td>31</td><td>IN</td><td>Clock in.</td></tr>
<tr><td>GND</td><td>5, 13, 21,
29, 53</td><td>Ground</td><td>Ground Pins for TTL inputs and digital circuitry.</td></tr>
<tr><td>LVDS VCC</td><td>44</td><td>Power</td><td>Power Supply Pins for LVDS Outputs.</td></tr>
<tr><td>LVDS GND</td><td>36, 43, 49</td><td>Ground</td><td>Ground Pins for LVDS Outputs.</td></tr>
<tr><td>PLL VCC</td><td>34</td><td>Power</td><td>Power Supply Pin for PLL circuitry.</td></tr>
<tr><td>PLL GND</td><td>33, 35</td><td>Ground</td><td>Ground Pins for PLL circuitry.</td></tr>
</table>

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Absolute Maximum Ratings [1]

Supply Voltage (V_{CC})	-0.3V ~ +4.0V
CMOS/TTL Input Voltage	-0.3V ~ (V_{CC} + 0.3V)
CMOS/TTL Output Voltage	-0.3V ~ (V_{CC} + 0.3V)
LVDS Driver Output Voltage	-0.3V ~ (V_{CC} + 0.3V)
Output Current	continuous
Junction Temperature	+125°C
Storage Temperature Range	-55°C ~ +150°C
Resistance to soldering heat	+260°C/10sec
Maximum Power Dissipation @+25°C	0.5W

Recommended Operating Conditions

Parameter	Min	Typ	Max	Units
All Supply Voltage	3.0	3.3	3.6	V
Operating Ambient Temperature	-40		85	°C
CLK IN Frequency	8		85	MHz

1. "Absolute Maximum Ratings" are those valued beyond which the safety of the device can not be guaranteed. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" specify conditions for device operation.

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Electrical Characteristics

CMOS/TTL DC Specifications

V_{CC} = VCC = PLL VCC = LVDS VCC

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{IH}	High Level Input Voltage	RS=VCC or GND	2.0		V_{CC}	V
V_{IL}	Low Level Input Voltage	RS=VCC or GND	GND		0.8	V
V_{DDQ}[1]	Small Swing Voltage		1.2		2.8	V
V_{REF}	Input Reference Voltage	Small Swing (RS=V_{DDQ}/2)		V_{DDQ}/2		
V_{SH}[2]	Small Swing High Level Input Voltage	V_{REF} = V_{DDQ}/2	V_{DDQ}/2 +100mV			V
V_{SL}[2]	Small Swing Low Level Input Voltage	V_{REF} = V_{DDQ}/2			V_{DDQ}/2 -100mV	V
I_{INC}	Input Current	$0V \le V_{IN} \le V_{CC}$			±10	uA

Notes: [1] V_{DDQ} voltage defines max voltage of small swing input. It is not an actual input voltage.
[2] Small swing signal is applied to TA0-6,TB0-6,TC0-6,TD0-6 and CLKIN.

LVDS Transmitter DC Specifications

V_{CC} = VCC = PLL VCC = LVDS VCC

Symbol	Parameter	Conditions		Min.	Typ.	Max.	Units
VOD	Differential Output Voltage	RL=100 Ω	Normal swing RS=V_{CC}	250	350	500	mV
			Reduced swing RS=GND	100	200	300	mV
ΔVOD	Change in VOD between complementary output states	RL=100 Ω				35	mV
VOC	Common Mode Voltage			1.125	1.25	1.375	V
ΔVOC	Change in VOC between complementary output states					35	mV
I_{OS}	Output Short Circuit Current	VOUT=0V, RL=100 Ω				-24	mA
I_{OZ}	Output TRI-STATE Current	/PDWN=0V, V_{OUT}=0V to V_{CC}				±10	uA

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Supply Current

V_{CC} = VCC = PLL VCC = LVDS VCC

Symbol	Parameter	Condition(*)		Typ.	Max.	Units
I_{TCCG}	Transmitter Supply Current	RL=100Ω,CL=5pF V_{CC}=3.3V, f=85MHz Gray Scale Pattern	RS=V_{CC}	52	58	mA
			RS=GND	40	46	mA
I_{TCCW}	Transmitter Supply Current	RL=100Ω,CL=5pF V_{CC}=3.3V, f=85MHz Worst Case Pattern	RS=V_{CC}	61	67	mA
			RS=GND	50	56	mA
I_{TCCS}	Transmitter Power Down Supply Current	/PDWN = L			10	uA

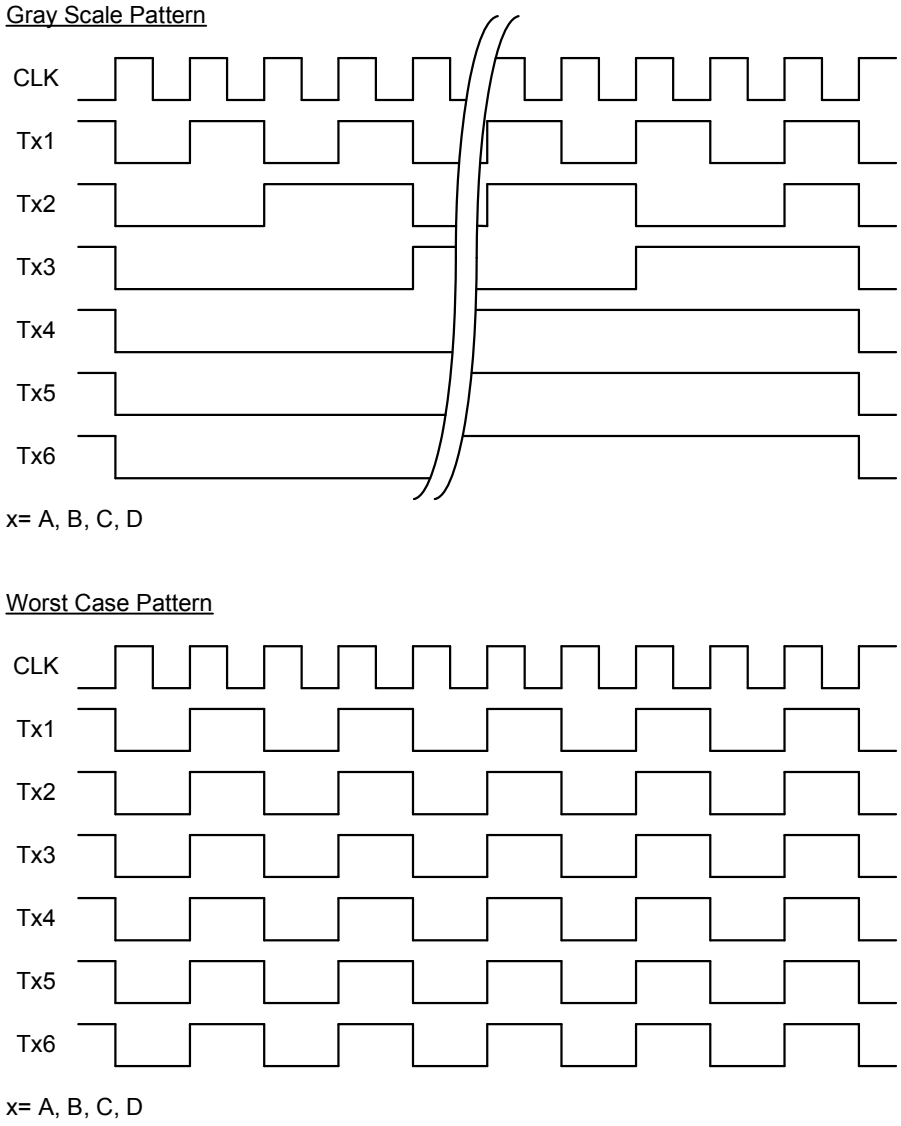

Fig1. Data Pattern

Switching Characteristics

V_{CC} = VCC = PLL VCC = LVDS VCC

Symbol	Parameter	Min.	Typ.	Max.	Units
t_{TCIT}	CLK IN Transition time			5.0	ns
t_{TCP}	CLK IN Period	11.7	T	125	ns
t_{TCH}	CLK IN High Time	0.35T	0.5T	0.65T	ns
t_{TCL}	CLK IN Low Time	0.35T	0.5T	0.65T	ns
t_{TCD}	CLK IN to TCLK+/- Delay		3T		ns
t_{TS}	TTL Data Setup to CLK IN	2.5			ns
t_{TH}	TTL Data Hold from CLK IN	0			ns
t_{LVT}	LVDS Transition Time		0.6	1.5	ns
t_{TOP1}	Output Data Position0 (T=11.7ns)	-0.2	0.0	+0.2	ns
t_{TOP0}	Output Data Position1 (T=11.7ns)	$\frac{T}{7}-0.2$	$\frac{T}{7}$	$\frac{T}{7}+0.2$	ns
t_{TOP6}	Output Data Position2 (T=11.7ns)	$2\frac{T}{7}-0.2$	$2\frac{T}{7}$	$2\frac{T}{7}+0.2$	ns
t_{TOP5}	Output Data Position3(T=11.7ns)	$3\frac{T}{7}-0.2$	$3\frac{T}{7}$	$3\frac{T}{7}+0.2$	ns
t_{TOP4}	Output Data Position4 (T=11.7ns)	$4\frac{T}{7}-0.2$	$4\frac{T}{7}$	$4\frac{T}{7}+0.2$	ns
t_{TOP3}	Output Data Position5 (T=11.7ns)	$5\frac{T}{7}-0.2$	$5\frac{T}{7}$	$5\frac{T}{7}+0.2$	ns
t_{TOP2}	Output Data Position6 (T=11.7ns)	$6\frac{T}{7}-0.2$	$6\frac{T}{7}$	$6\frac{T}{7}+0.2$	ns
t_{TPLL}	Phase Lock Loop Set			10.0	ms

AC Timing Diagrams

TTL Input

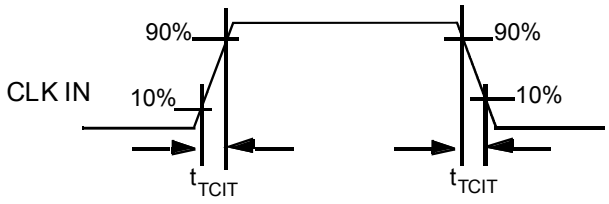

Fig2. CLKIN Transition Time

LVDS Output

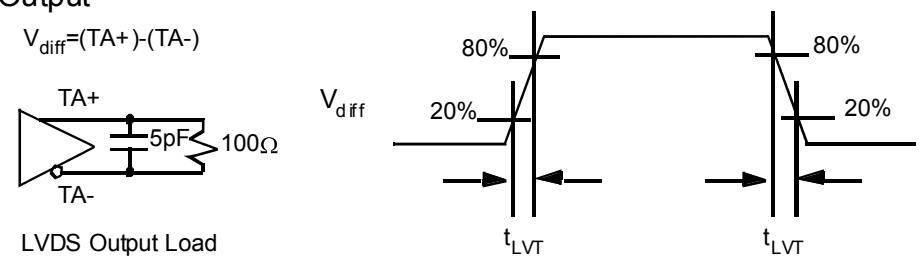

Fig3. LVDS Output Load and Transition Time

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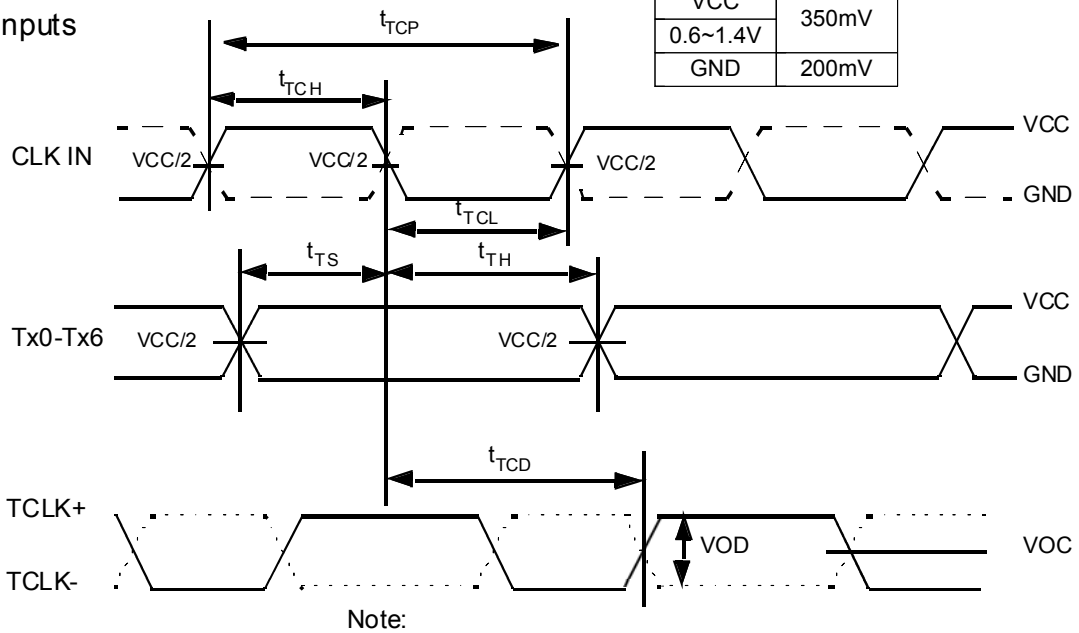
TTL Inputs

RS Pin	VOD
VCC	350mV
0.6~1.4V	
GND	200mV

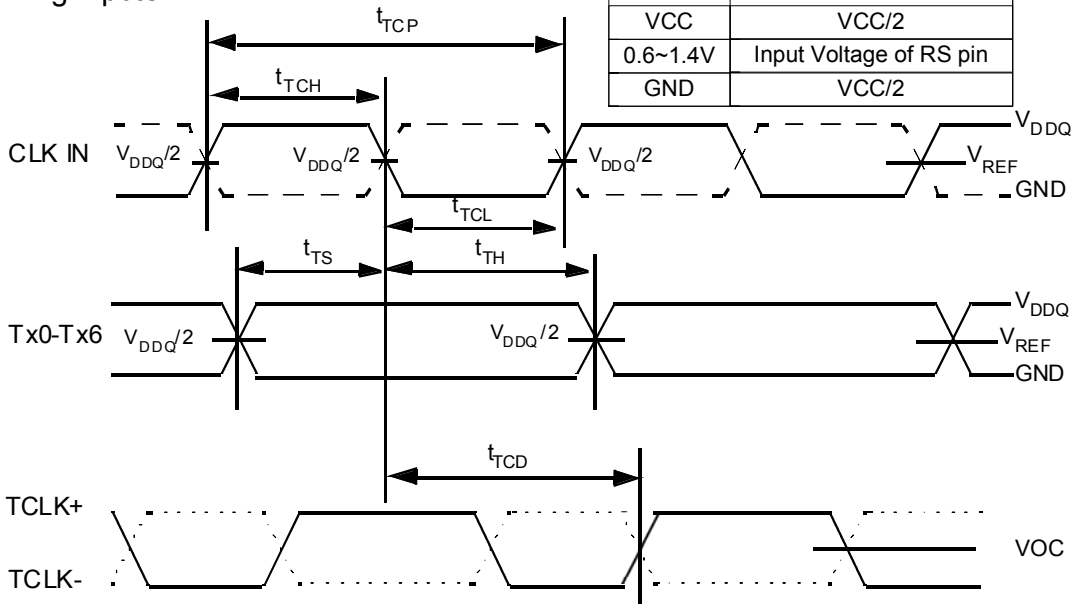


Note:
CLK IN: for R/F=GND, denote as solid line,
for R/F=VCC, denote as dashed line.

Fig4. CLKIN Period, High/Low Time, Setup/Hold Timing

Small Swing Inputs

RS Pin	VREF
VCC	VCC/2
0.6~1.4V	Input Voltage of RS pin
GND	VCC/2



Note:
CLK IN: for R/F=GND, denote as solid line,
for R/F=VCC, denote as dashed line.

Fig5. Small Swing Inputs

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AC Timing Diagrams

LVDS Output

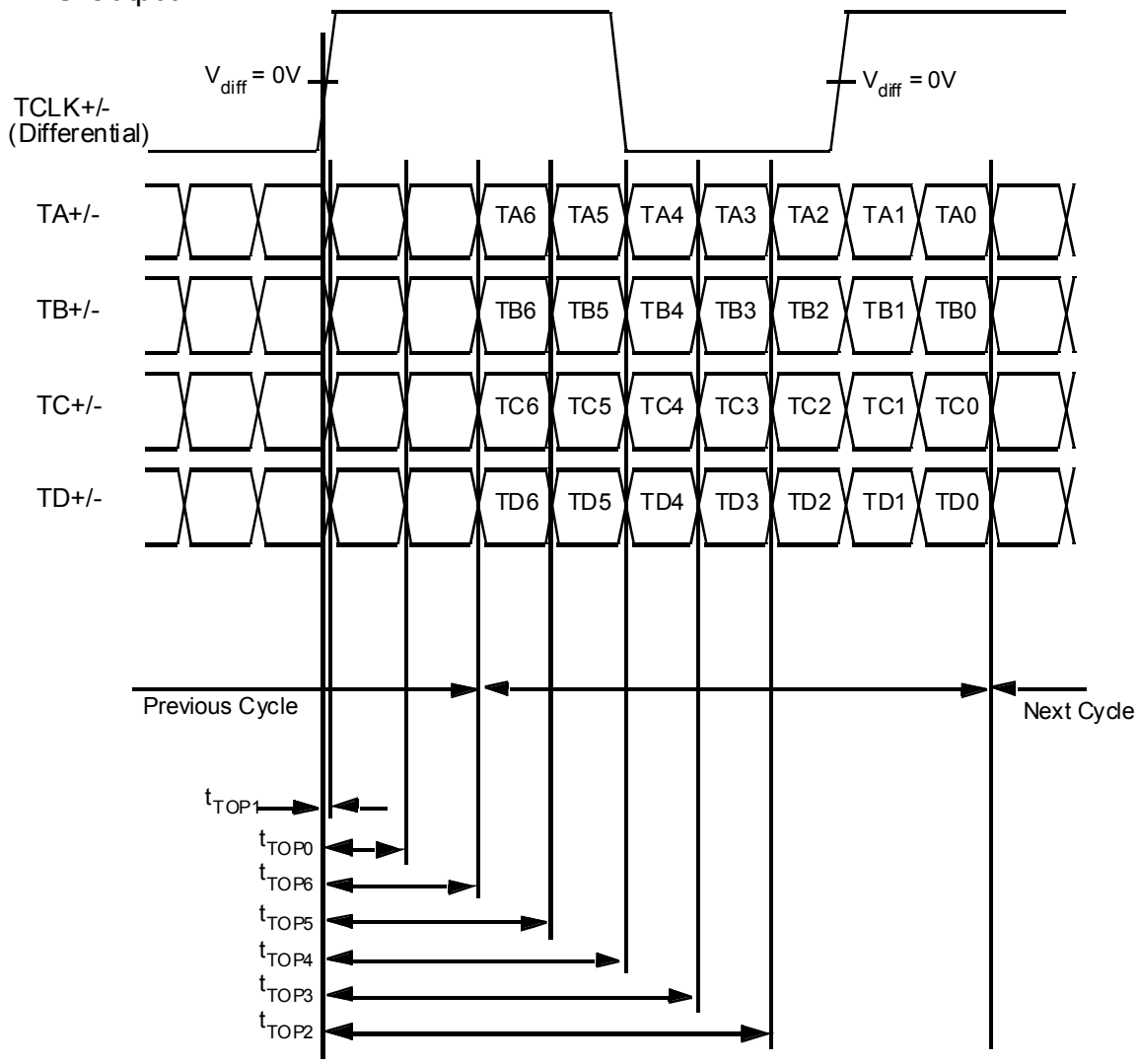


Fig6. LVDS Output Data Position

Phase Lock Loop Set Time

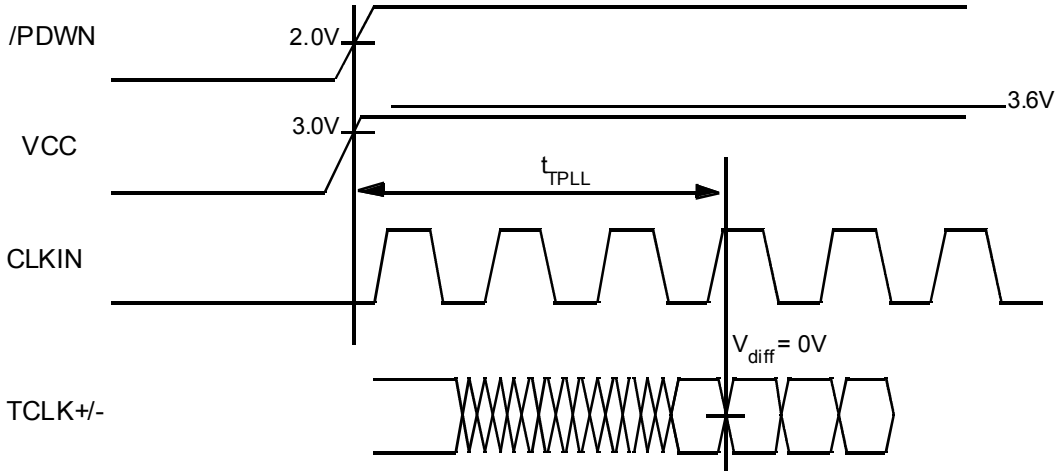


Fig7. PLL Lock Set Time

Note

1)Cable Connection and Disconnection

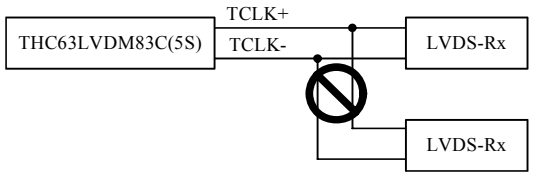
Don't connect and disconnect the LVDS cable, when the power is supplied to the system.

2)GND Connection

Connect the each GND of the PCB which THC63LVDM83C(5S) and LVDS-Rx on it. It is better for EMI reduction to place GND cable as close to LVDS cable as possible.

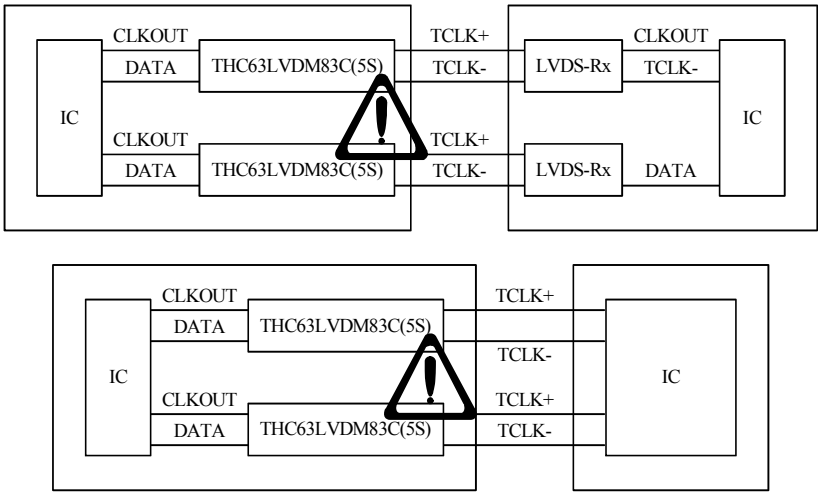
3)Multi Drop Connection

Multi drop connection is not recommended.



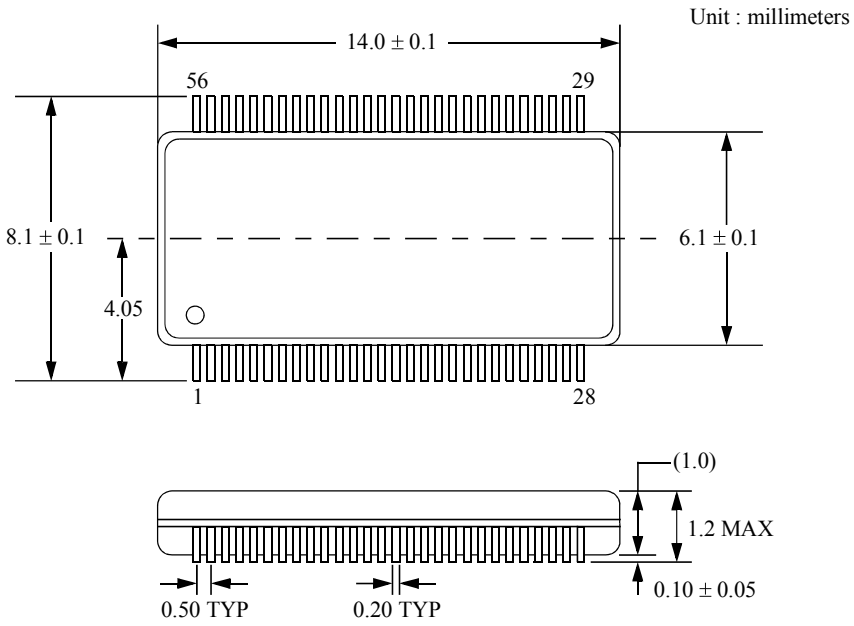
4)Asynchronous use

Asynchronous use such as following systems are not recommended.



Package

56 Lead Molded Thin Shrink Small Outline Package, JEDEC



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THine Electronics, Inc.
E-mail: sales@thine.co.jp

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